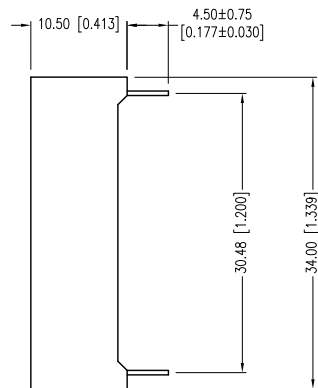
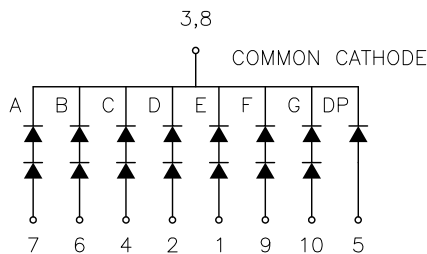
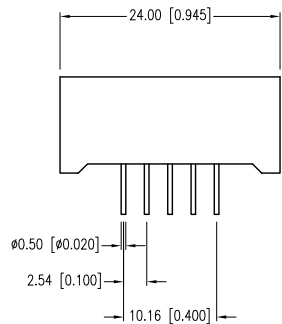
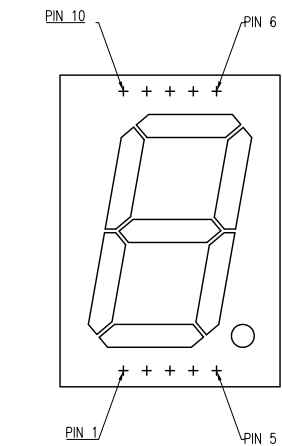
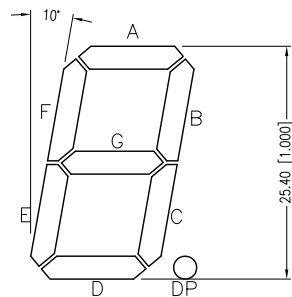




DIGIT DETAIL



PART NUMBER	LDS-CA12RI	REV.	B
DATE	E.C.N. NUMBER AND REVISION COMMENTS		REV.
04.22.98	E.C.N. #10BRDR. & REDRAWN.		A
01.03.13	E.C.N. #10BRDR. & REDRAWN.		B

A

ELECTRO-OPTICAL CHARACTERISTICS Ta=25°C If=10mA

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH (G)		565		nm	
FORWARD VOLTAGE		4.4/2.2	5.2/2.6	Vf	
REVERSE VOLTAGE	5.0			Vr	Ir=100µA
AXIAL INTENSITY		6300		µcd	If=10mA
EMITTED COLOR:	GREEN				
FONT COLOR:	GREY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-20 TO +80	°C
STORAGE TEMP.	-20 TO +80	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY	3	SEC.

* t<10µS

RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DATE:	01.03.13	DRAWN BY:	MA
PAGE:	1 OF 1	CHKD BY:	KF
SCALE:	NTS	APRVD BY:	KF
UNIT:	mm [INCH]		Ⓟ